



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Pavilion Elite HPE PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	9
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		7
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
NEPTUNE2_HPE_TRIM_BEZEL	trim bezel	44.65g	>ABS<	
NEPTUNE2_PMD_BLANK_BEZEL	removeable hdd cage cover	39g	>ABS<	
NEPTUNE2_HPE_COSMETIC_BEZEL	cosmetic bezel	33.67g	>ABS<	
NEPTUNE2_MAIN_BEZEL	main bezel	235.14g	>ABS<	
NEPTUNE2_TOP_CAP_BASE	top cover	214.5g	>ABS<	
Fan Frame	CPU fan frame	35.6g	>PBT-GF30-FR(17)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 cross screw driver	1
Description #2 clipper	1
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

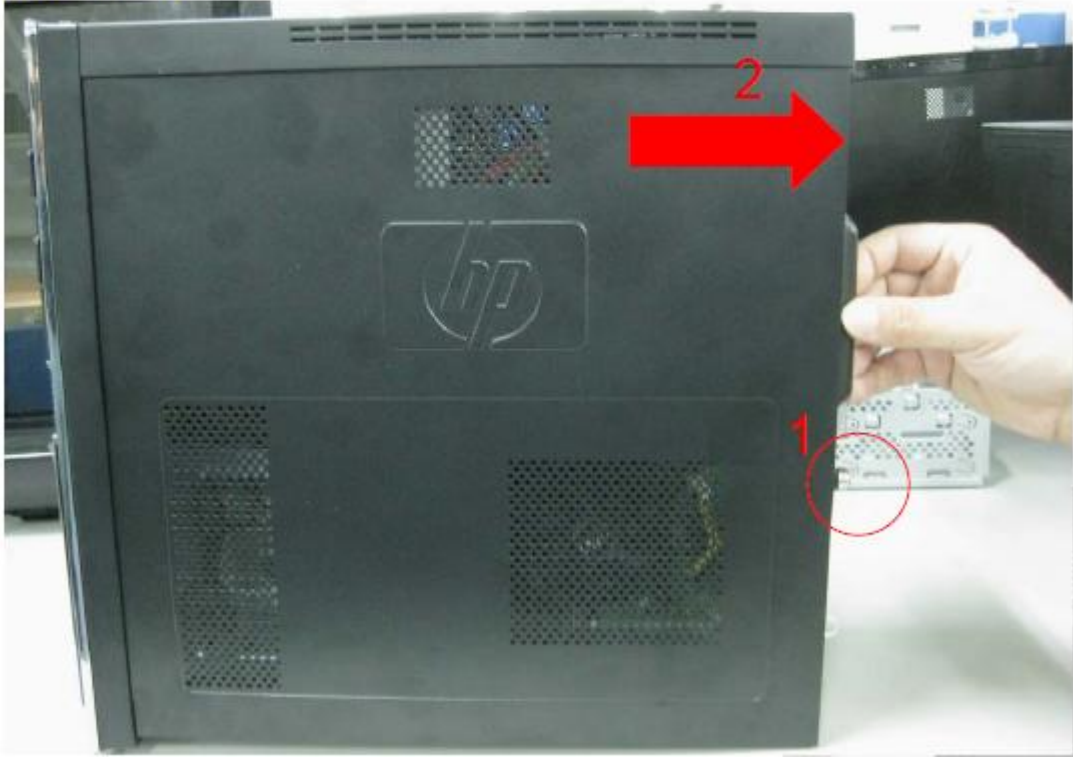
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Refer to disassembly graphic below
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Remove side cover

1. Unfix thumbscrew 1 pcs.
2. Remove side cover



2. Remove main bezel

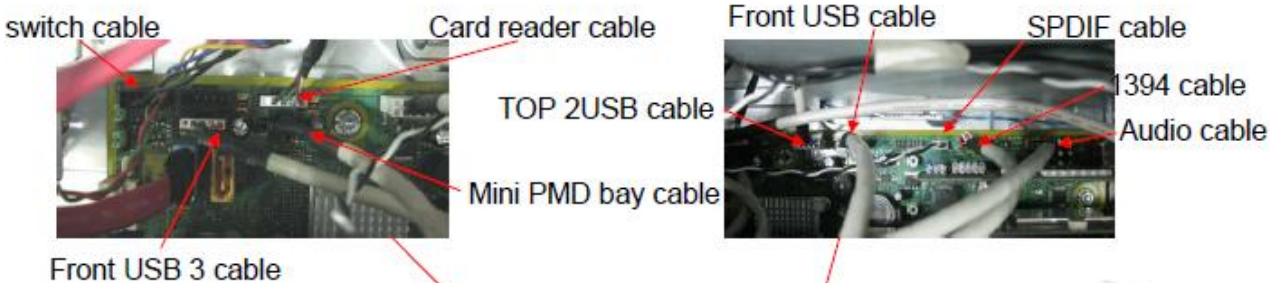
1. Release main bezel hook 1,2,3.
2. Take out main bezel



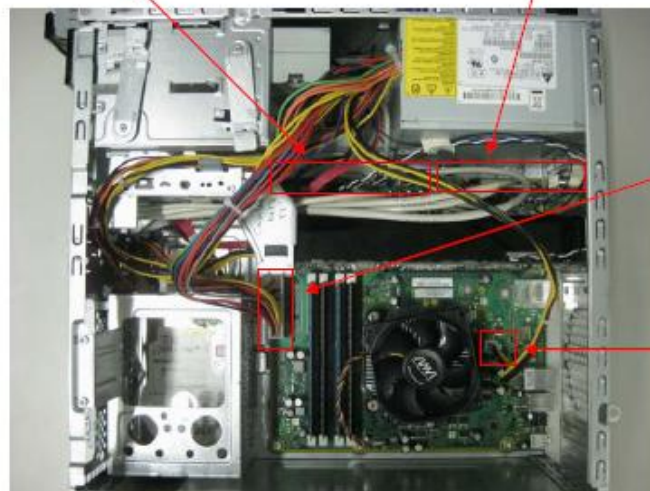
3. Unplug all cable

Unplug:

1. Power cable (24pin)
2. Heat sink fan cable
3. 12V power cable (4pin)
4. Audio cable
5. Front USB, card reader and switch cable
6. HDD data and power cable
7. ODD data and power cable
8. TOP 2USB cable
9. Front USB 3 cable
10. Mini PMD bay cable
11. 1394 cable
12. Wireless lamp cable
13. GFX support bracket



Front USB 3 cable



power cable (24pin)



12V power cable (4pin)



GFX support bracket



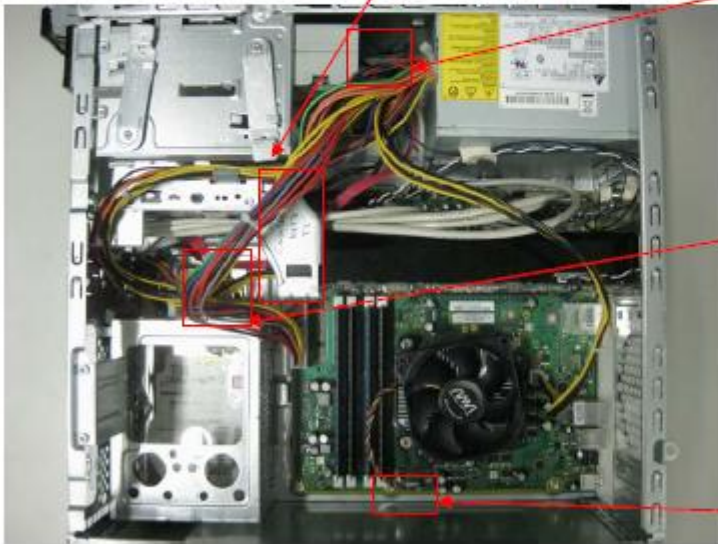
ODD data and power cable



HDD data and power cable



Heat sink fan cable



4. Remove front I/O module

1. Unfix 2 screw from chassis.
2. Unlock cable mount
3. Remove front I/O module.



5 .Remove Add-on card

- 1.Unfix 2 screw and remove PCI slot clamp
- 2.Release GFX power cable(6pin)
- 3.Release latch of PCI-Ex16 slot
- 4.Unplug VGA card
- 5.Unplug wireless card (saffron) and release wireless,wireless LED cable
- 6.Unplug TV tuner card

Unfix 2 screw and remove PCI slot clamp



Release GFX power cable (6pin)

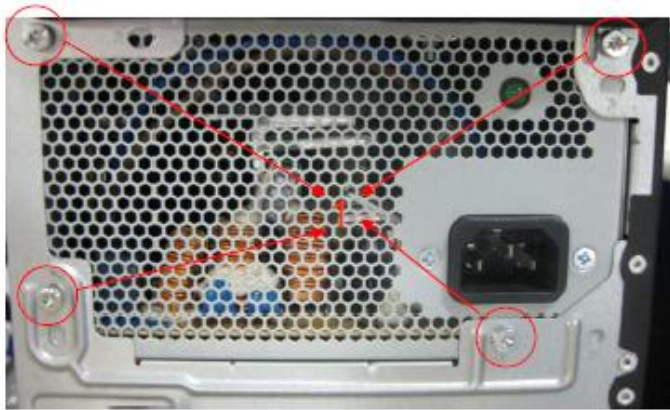


Release latch of PCI-Ex16 slot



6 .Remove PSU

- 1.Unfix 4 screw from chassis.
- 2.Press latch of chassis
- 3.Remove PSU from chassis.

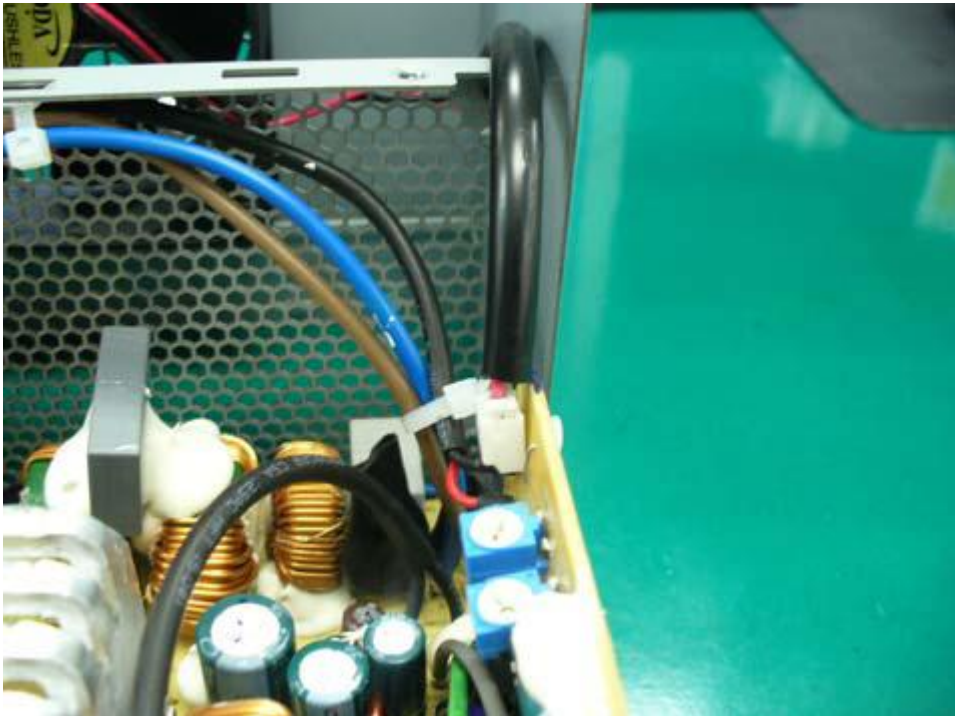


Attachment 1 --Product Disassembly Drawing

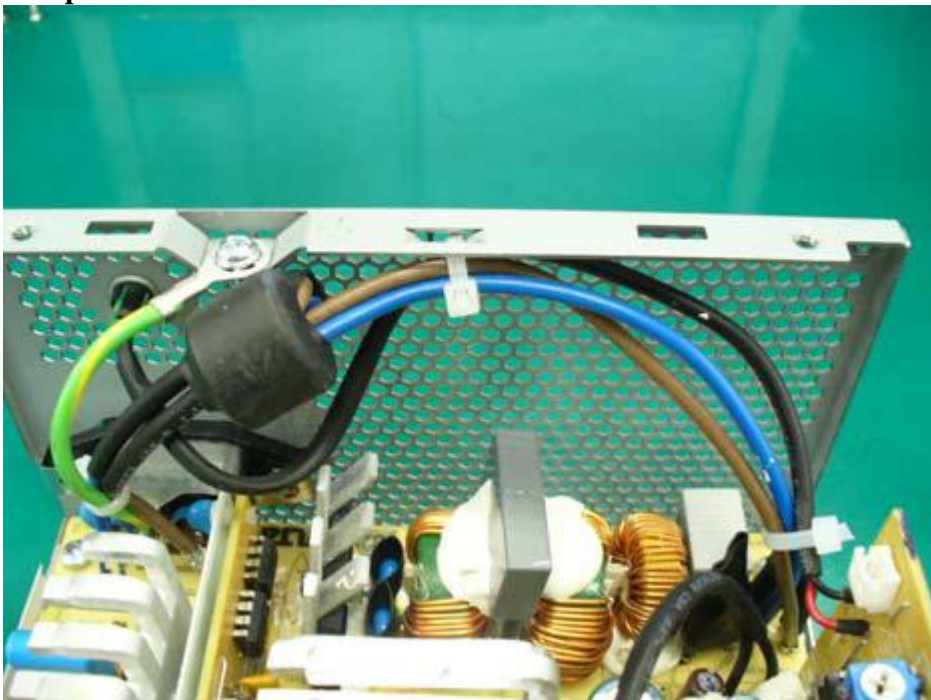


1. Remove 4 screws by screwdriver to remove top cover.

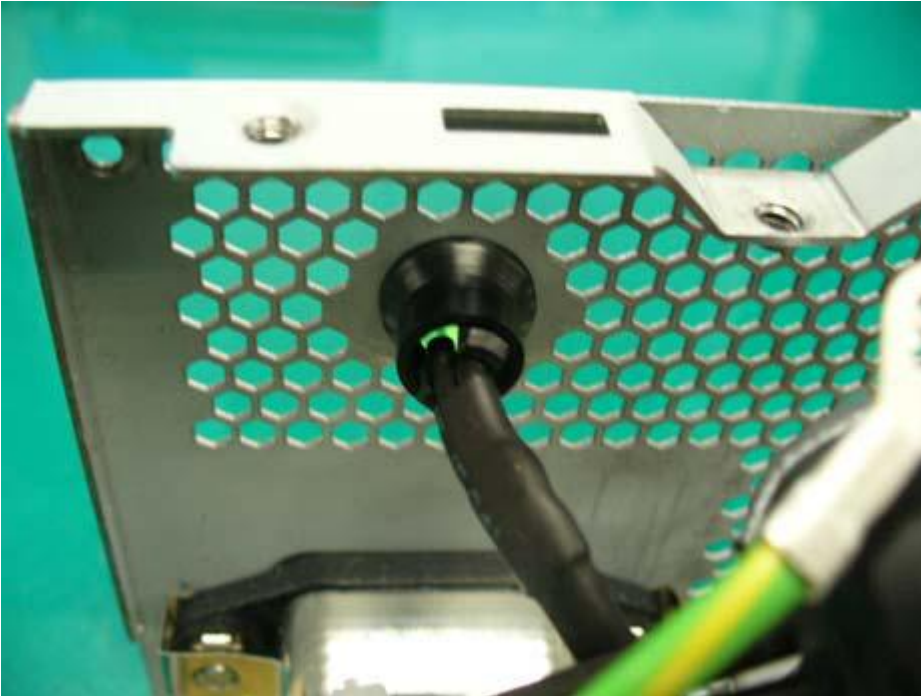
EL-MF877-00
Template Revision B



2. Separate Fan connector from PCB.



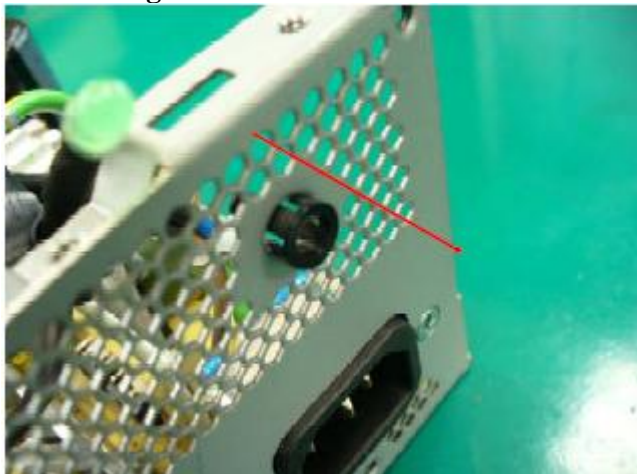
3. Remove screw and cable tip by screwdriver and diagonal cutting pliers.



4. Remove LED holder by needle nose pliers.

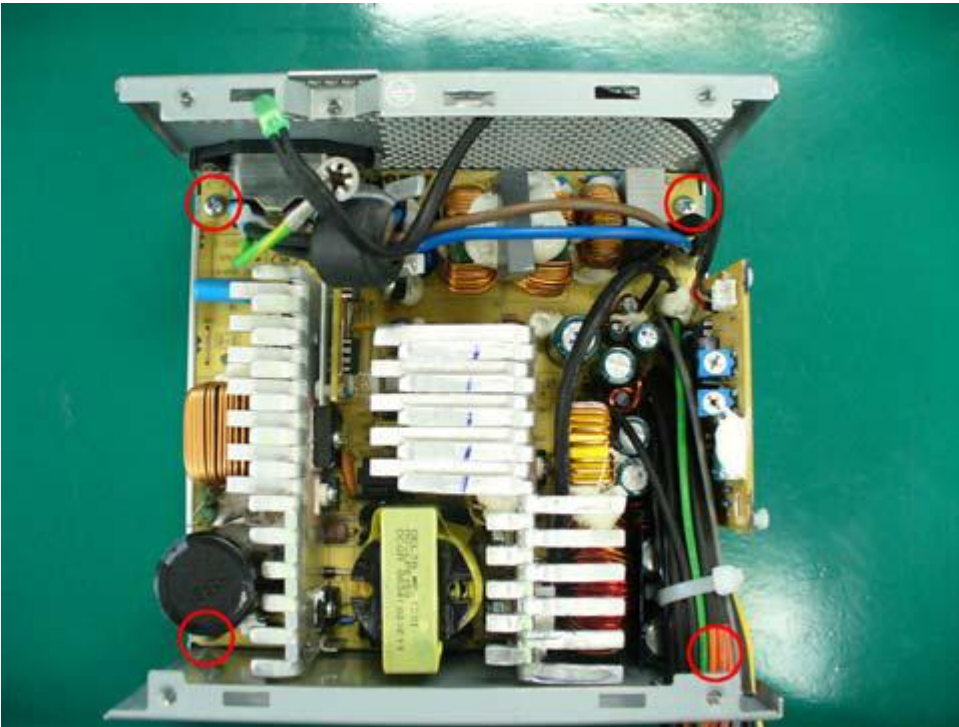


5. according to the arrow to take out the LED

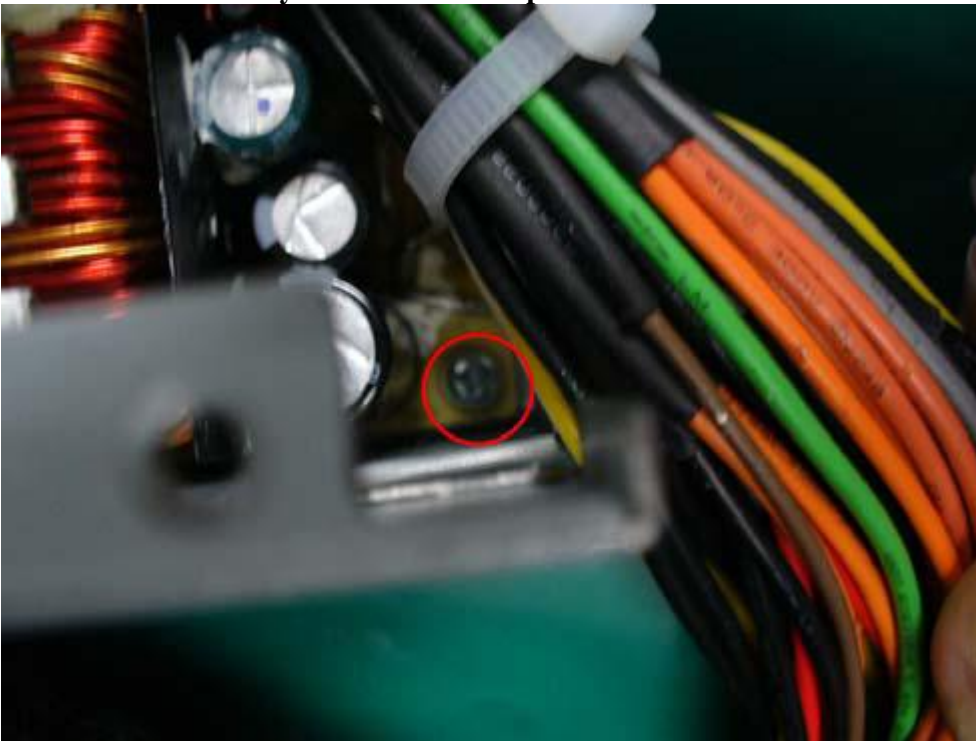


6. Remove LED holder.

EL-MF877-00
Template Revision B



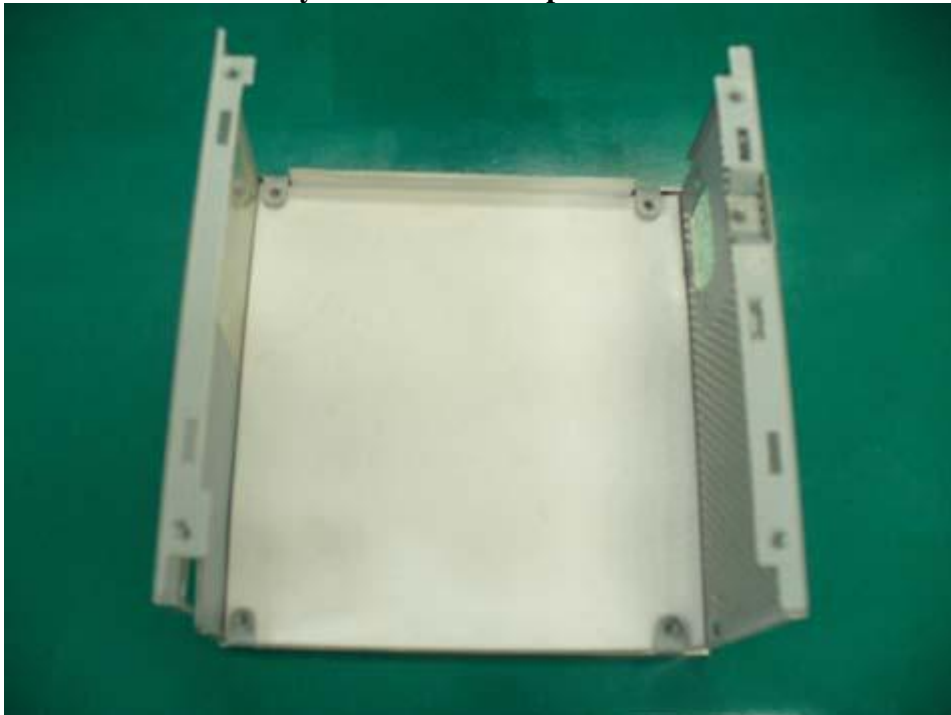
7. Remove 4 screws by screwdriver to separate PCB from case



8. Remove the screw under cable by screwdriver to separate PCB from case.



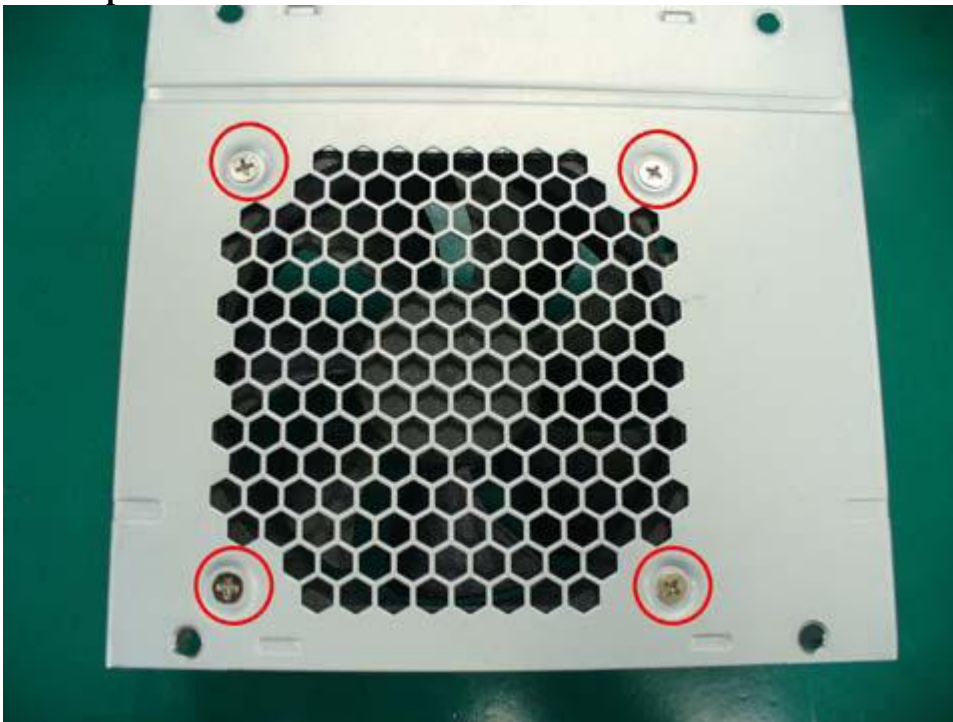
9. Remove 2 screws by screwdriver to separate socket from case



10. Separate PCB from case.



11. Separate insulator film from case.



12. Remove 4 screws by screwdriver to separate fan from top cover

Attachment 2 – Capacitor Granter Than 2.5 cm Location Drawing



C1

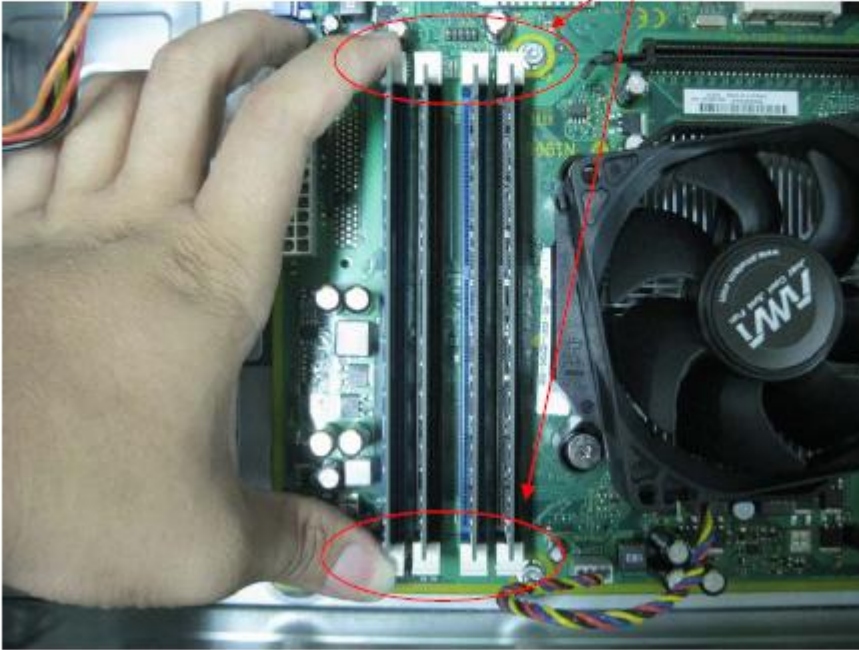


C951、C303、C302、C102、C103、C153

7 .Remove DIMM

- 1.Release latch of DIMM slot
- 2.Remove DIMMX4

Release latch of DIMM slot



8. Remove Heat Sink

1. Unfix 4 screw from Heat Sink

2. Remove Heat Sink



9 .Remove MB

1.Unfix 7 screw from chassis

2.Remove MB from chassis



Remove coin battery
from MB

